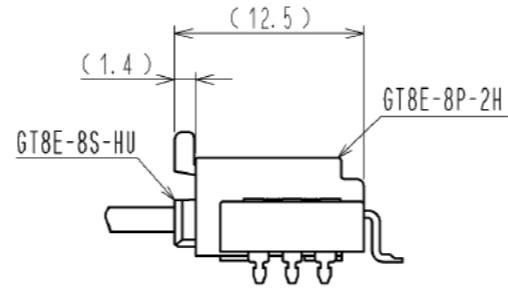
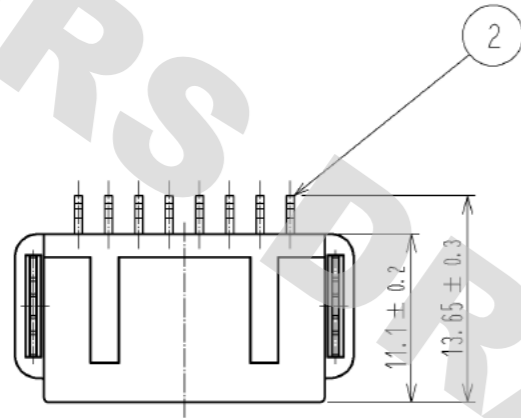
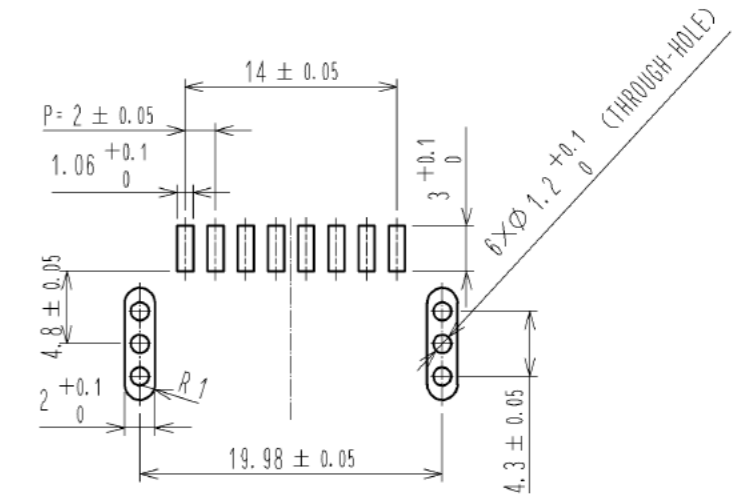


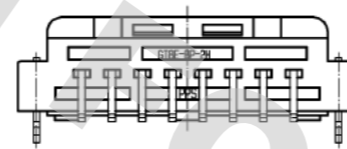
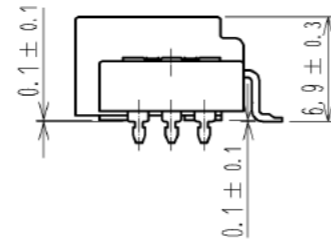
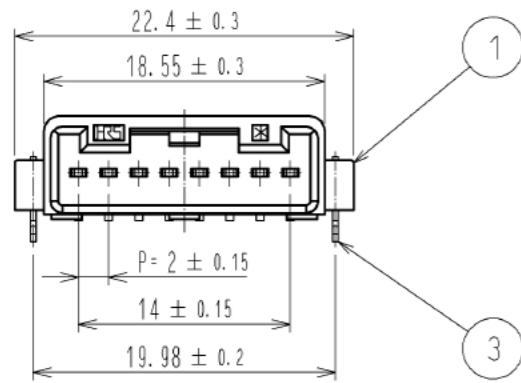
ELV. RoHS COMPLIANT



MATING CONFIGURATION



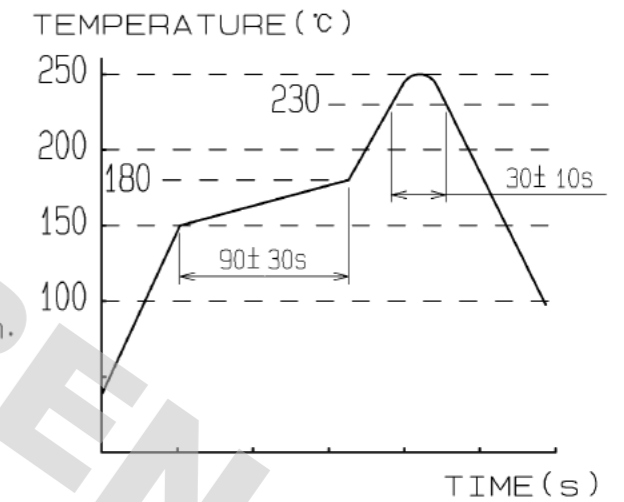
RECOMMENDED PC BOARD PATTERN



NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)
REFLOW HEATING METHODS: FAR-INFLARED, IN THE AIR OR NITROGEN

REFLOW No. : MAX 2TIMES
PEAK TEMPERATURE: 250°C
ABOVE 230°C: 20~40s
PREHEAT: 150~180°C
60~120s

- 2. SOLDERING TEMPERATURE: 280~300°C, MAX 2S
- 3. COPLANARITY OF LEADS SHALL BE UNDER 0.1mm.
- 4. RECOMMENDED THICKNESS FOR PC BOARD IS 1.6mm.
- 5. RECOMMENDED THICKNESS FOR SOLDER PASTE IS 0.15mm.



2	BRASS	TIN-COPPER ALLOY PLATING			
1	PPS	BLACK	3	BRASS	TIN-COPPER ALLOY PLATING
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : AR. SHIRAI	12.05.25	DRAWING NO. EDC3-167882-00	
		CHECKED : NA. HARUBAYASHI	12.05.25	PART NO. GT8E-8P-2H	
		DESIGNED : HH. TSUKUMO	12.05.25	CODE NO. CL758-1006-7-00	
		DRAWN : HH. TSUKUMO	12.05.25		

DRAWING FOR REFERENCE: This is subject to change without notice
05/31/2013